

SAL1 SERIES

(1.00 mm) .0394"

HIGH-SPEED THROUGH BOARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SAL1

Insulator Material:

Black LCP
Contact Material:
BeCu

Plating:

Au or Sn over

50 μm (1.27 μm) Ni

Operating Temp:

-55 °C to +125 °C

Current Rating:

2.9 A per pin

(2 adjacent pins powered)

RoHS Compliant: Yes

Mates with:

(1.60 mm) .062" or
(2.36 mm) .093" card

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

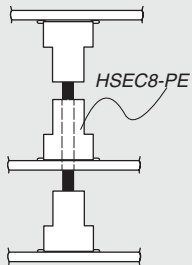
(0.10 mm) .004" max

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



OTHER SOLUTIONS



- Card pass-through option. See HSEC8-PE Series.

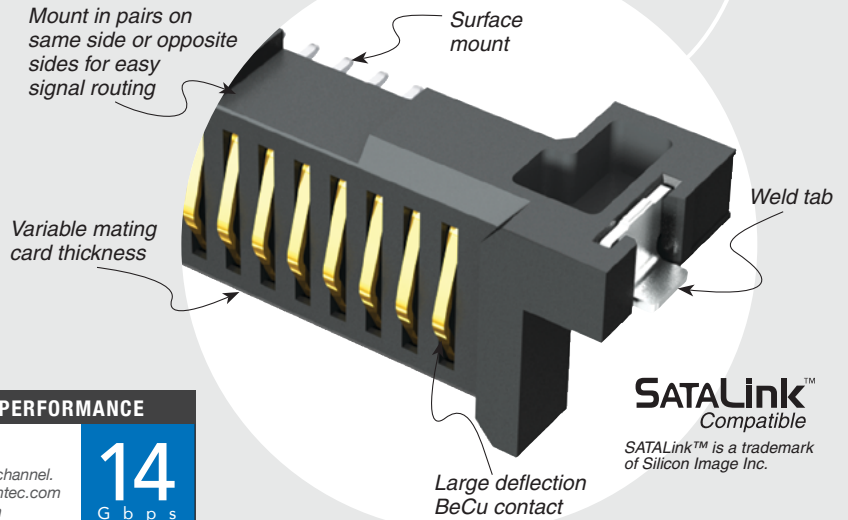
ALSO AVAILABLE (MOQ Required)

- Heavy Gold plating

Notes:

While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.

Some lengths, styles and options are non-standard, non-returnable.



HIGH-SPEED CHANNEL PERFORMANCE

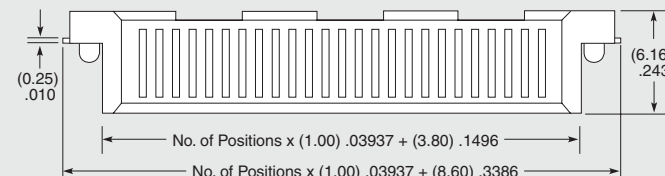
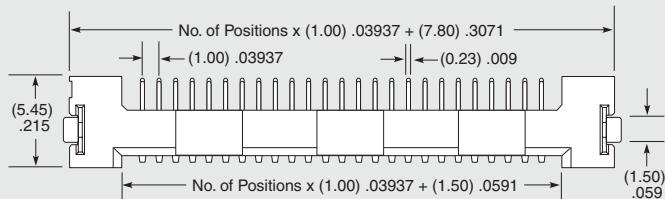
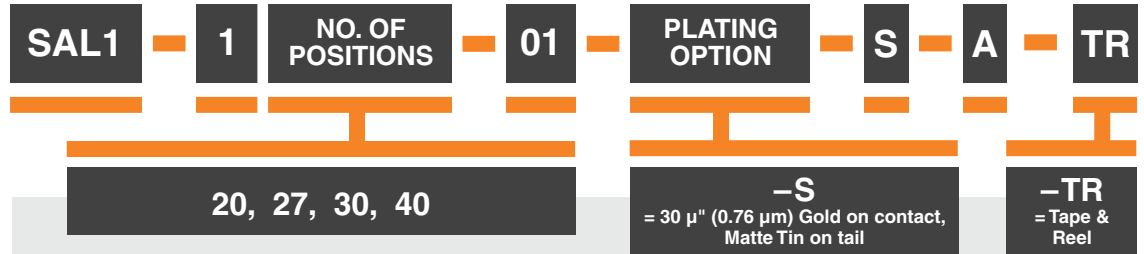
SAL1 (Top Entry)

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

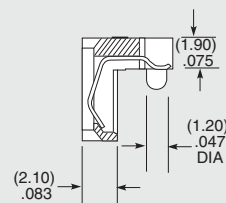
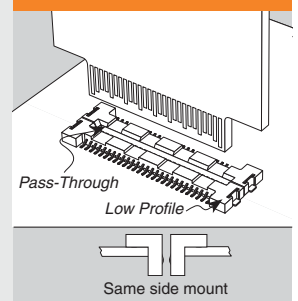
14
Gbps

SATALink™
Compatible

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APPLICATIONS



Due to technical progress, all designs, specifications and components are subject to change without notice.